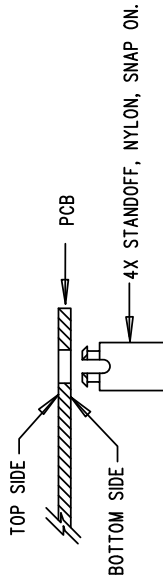


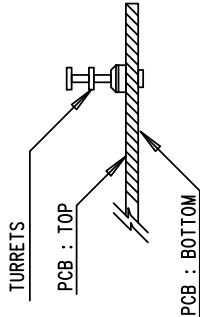
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	N.HARA	4-05-23


NOTES: UNLESS OTHERWISE SPECIFIED

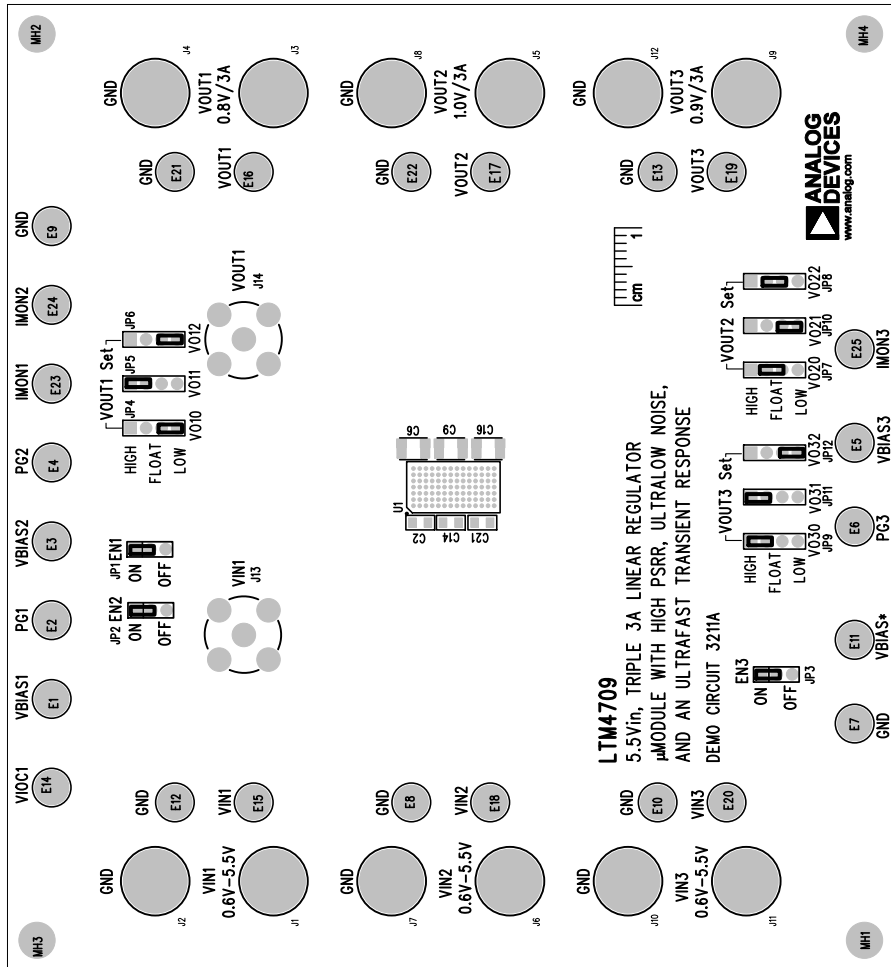
1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP
TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



3. INSTALL TURRETS AS SHOWN BELOW:



APPROVALS		 ANALOG DEVICES www.analog.com	
PCB DES.	HZ	TITLE: TOP ASSEMBLY DRAWING 5.5Vin, TRIPLE 3A LINEAR REGULATOR μMODULE WITH HIGH PSRR, AND AN ULTRAFAST TRANSIENT RESPONSE	
HAPP ENG.	N.HARA		
		SIZE IC NO. LTM4709E-Y N/A DEMO CIRCUIT 3211A	REV. 2
SCALE = NONE		FILENAME: DC3211A2.PCB SHT 1 OF 2	



TOP SILKSCREEN